

FEATURES

- High performance CMOS.
- Single +5 volt power supply.
- Adds or deletes standard asynchronous communication bits (start, stop, and parity) to or from serial data stream.
- Independently controlled transmit, receive, line status, and data set interrupts.
- Programmable baud generator allows division of any input clock by 1 to $(2^{16}-1)$ and generates the internal 16 x clock.
- Full double buffering eliminates need for precise synchronization.
- Independent receiver clock input.
- Complete status reporting capabilities.
- False start bit detection.
- MODEM control functions ($\overline{\text{CTS}}$, $\overline{\text{RTS}}$, $\overline{\text{DSR}}$, $\overline{\text{DTR}}$, $\overline{\text{RI}}$, and DCD).
- Fully programmable serial-interface characteristics:
 - 5-, 6-, 7-, or 8-bit characters.
 - Even, odd, or no-parity bit generation and detection.
 - 1-, 1½-, or 2-stop bit generation.
 - Baud generation (DC to 56k baud).
- Line break generation and detection.
- Internal diagnostic capabilities:
 - Loopback controls for communications link fault isolation.
 - Break, parity, overrun, framing error simulation.
- Full prioritized interrupt system controls.
- All inputs and outputs are TTL compatible.
- Easily interface to most popular microprocessors.

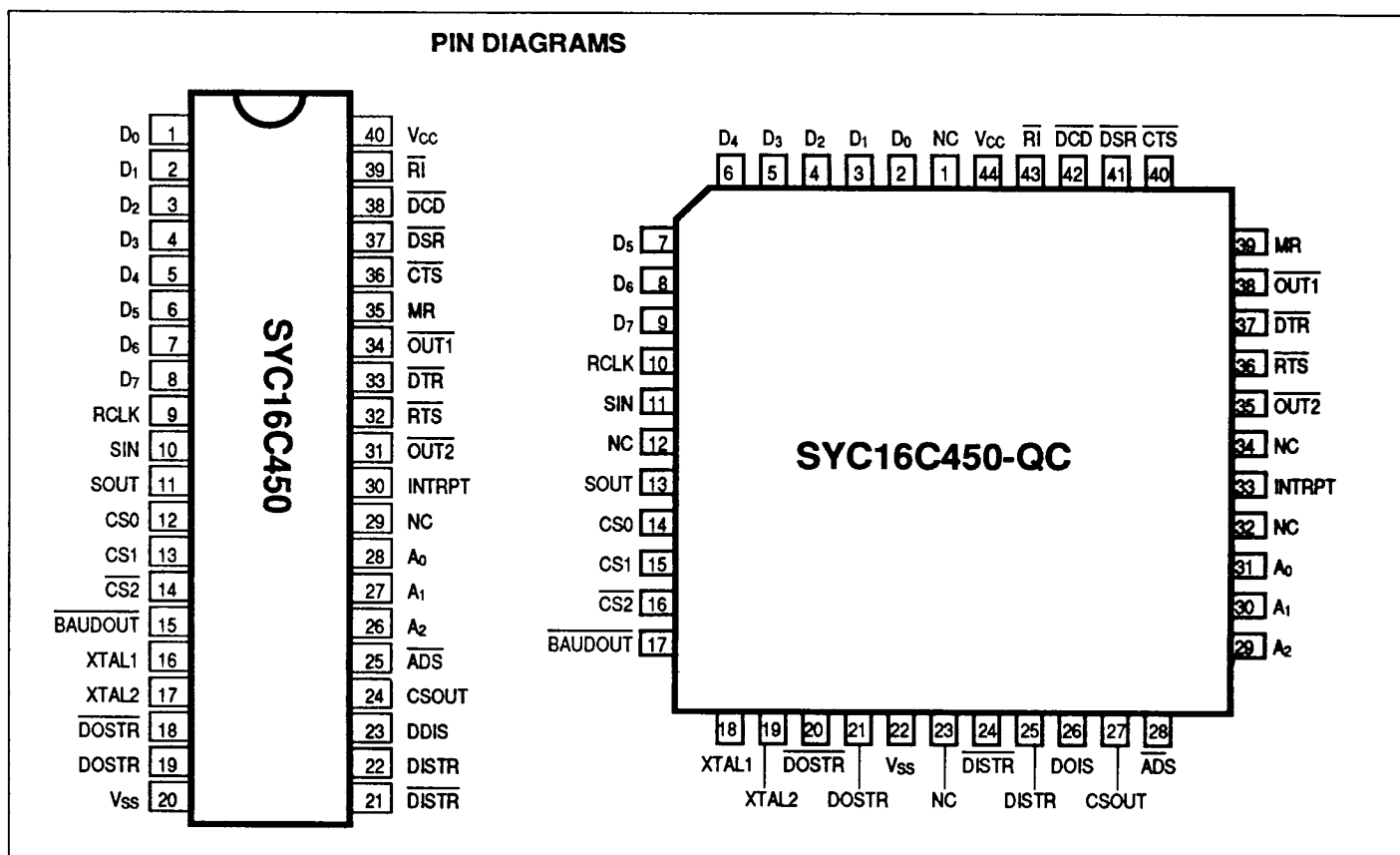
GENERAL DESCRIPTION

The SYC16C450 is a programmable Asynchronous Communication Element (ACE) chip fabricated using high performance CMOS process. The SYC16C450 performs serial-to-parallel conversion on data characters received from a peripheral device or a MODEM, and parallel-to-serial conversion on data characters received from CPU. The complete status of the SYC16C450 can be read at any time during functional operation by the CPU. The information obtained includes the type and condition of the trans-

fer operations being performed, and error conditions involving parity, overrun, framing or break interrupt.

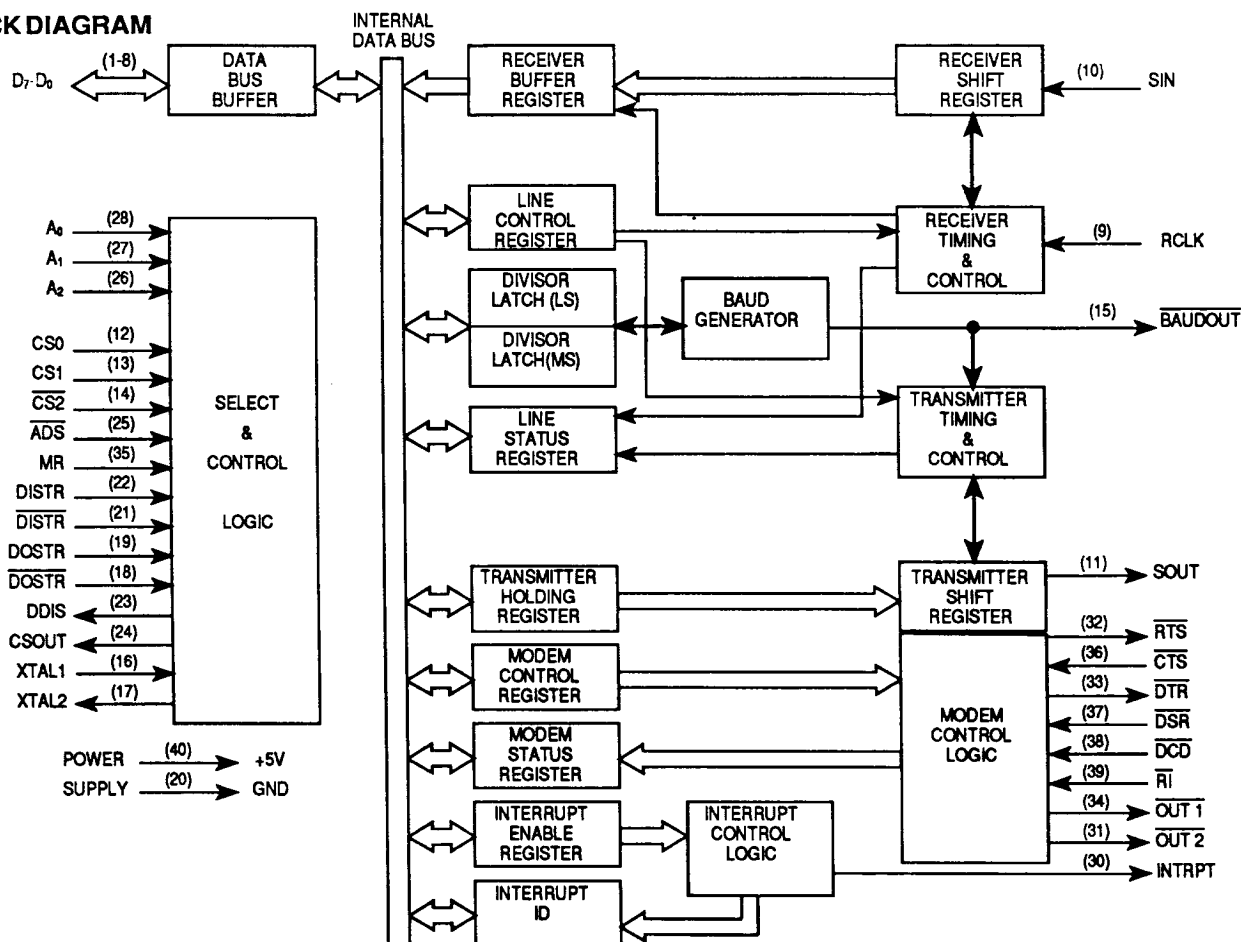
A programmable baud rate generator is included that can divide the timing reference clock input by a divisor between 1 and $(2^{16}-1)$. Also included in the SYC16C450 is a complete MODEM-control capability, and a processor-interrupt system that may be software tailored to the user's requirement to minimize the computing required to handle the communications link.

PIN DIAGRAMS





BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Ambient Temperature under Bias	0°C to +70°C
Storage Temperature	-65°C to +150°C
Voltage on any I/O pin with Respect to Ground	-0.5V to +7.0V
Power Dissipation	700mW

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated on the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS $T_A = 0^\circ\text{C to } +70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$, $V_{SS} = 0\text{ V}$, unless otherwise specified

Symbol	Parameter	SYC16C450		Units	Conditions
		Min	Max		
VILX	Clock input LOW Voltage	-0.5	0.8	V	
VIHX	Clock input HIGH Voltage	2.0	VCC	V	
VIL	Input LOW Voltage	-0.5	0.8	V	
VIH	Input HIGH Voltage	2.0	VCC	V	
VOL	Output LOW Voltage		0.4	V	IOL = 1.6 mA on all Note 1
VOH	Output HIGH Voltage	2.4		V	IOH = -1.0 mA Note 1
ICC (Avg)	Average Power Supply Current (VCC)		20	mA	VCC = 5.25 V, No loads on SIN, DSR, RLSD, CTS, DCD, RI = 2.0 V. All other inputs = 0.8 V. Baud rate generator at 4 MHz. Baud rate at 56K.
IIL	Input Leakage		± 10	µA	VCC = 5.25 V, VSS = 0 V. All other pins floating.
ICL	Clock Leakage		± 10	µA	VIN = 0 V, 5.25 V
IOZ	3-state Leakage		± 20	µA	VCC = 5.25 V, VSS = 0 V. VOUT = 0 V, 5.25 V 1) Chip deselected 2) Chip and write mode selected
VILMR	MR Schmitt VIL		0.8	V	
VIHMR	MR Schmitt VIH	2.0		V	

CAPACITANCE $T_A = 25^{\circ}\text{C}$, $f = 1.0\text{ MHz}$, $V_{CC} = V_{SS} = 0\text{ V}$

Symbol	Parameter	Min	Typ	Max	Units	Conditions
CXTAL2	Clock Input Capacitance		15	20	pF	$f_c = 1\text{ MHz}$ Unmeasured pins returned to VSS
CXTAL1	Clock Output Capacitance		20	30	pF	
CI	Input Capacitance		6	10	pF	
CO	Output Capacitance		10	20	pF	

AC CHARACTERISTICS $T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$, Note 5

Symbol	Parameter	SYC16C450		Units	Conditions
		Min	Max		
t_{AW}	Address Strobe Width	60		ns	
t_{AS}	Address Setup Time	60		ns	
t_{AH}	Address Hold Time	0		ns	
t_{CS}	Chip Select Setup Time	60		ns	
t_{CH}	Chip Select Hold Time	0		ns	
t_{CSS}	Chip Select Output Delay From $\overline{ADS}$			ns	
t_{DD}	$\overline{DISTR}/\overline{DISTR}$ Delay From $\overline{ADS}$			ns	
t_{DW}	$\overline{DISTR}/\overline{DISTR}$ Strobe Width	125		ns	
t_{RC}	Ready Cycle Delay	175		ns	
RC	Ready Cycle = $t_{AR}(1) + t_{DW} + t_{RC}$	360		ns	
t_{DD}	$\overline{DISTR}/\overline{DISTR}$ to Driver Disable Delay		60	ns	100 pF load, Note 4
t_{DD}	Delay from $\overline{DISTR}/\overline{DISTR}$ to Data		125	ns	100 pF load
t_{HZ}	$\overline{DISTR}/\overline{DISTR}$ to Floating Data Delay	0	100	ns	100 pF load, Note 4
t_{DOD}	$\overline{DOSTR}/\overline{DOSTR}$ delay from $\overline{ADS}$			ns	
t_{DOW}	$\overline{DOSTR}/\overline{DOSTR}$ Strobe Width	100		ns	
t_{WC}	Write Cycle Delay	200		ns	
WC	Write Cycle = $t_{AW} + t_{DOW} + t_{WC}$	360		ns	
t_{DS}	Data Setup Time	40		ns	
t_{DH}	Data Hold Time	40		ns	
t_{CSC}^*	Chip Select Output Delay from Select		100	ns	100 pF load
t_{RA}^*	Address Hold Time from $\overline{DISTR}/\overline{DISTR}$	20		ns	Note 2
t_{RCS}^*	Chip Select Hold Time from $\overline{DISTR}/\overline{DISTR}$	20		ns	Note 2
t_{AR}^*	$\overline{DISTR}/\overline{DISTR}$ Delay from Address	60		ns	Note 2
t_{CSR}^*	$\overline{DISTR}/\overline{DISTR}$ Delay from Chip Select	50		ns	Note 2
t_{WA}^*	Address Hold Time from $\overline{DOSTR}/\overline{DOSTR}$	20		ns	Note 2
t_{WCS}^*	Chip Select Hold Time from $\overline{DOSTR}/\overline{DOSTR}$	20		ns	Note 2
t_{AW}^*	$\overline{DOSTR}/\overline{DOSTR}$ Delay from Address	60		ns	Note 2
t_{CSW}^*	$\overline{DOSTR}/\overline{DOSTR}$ Delay from Select	50		ns	Note 2
t_{MRW}	Master Reset Pulse Width	5		μs	
t_{XH}	Duration of Clock HIGH Pulse	140		ns	
t_{XL}	Duration of Clock LOW Pulse	140		ns	External Clock (3.1 MHz Max.)

**AC CHARACTERISTICS (Cont.)** $T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$, $V_{CC} = 5\text{ V} \pm 5\%$

		SYC16C450			
Symbol	Parameter	Min	Max	Units	Conditions
Transmitter					
t _{HR1}	Delay from rising edge of DOSTR/DOSTR (WR THR) to Reset Interrupt		175	ns	100 pF load
t _{HR2}	Delay from falling edge of DOSTR/DOSTR (WR THR) to Reset Interrupt		n/a	ns	100 pF load
t _{RS}	Delay from initial INTR Reset to Transmit Start	8	24	RCLK Cycles	Note 3
t _{SI}	Delay from Initial Write to Interrupt	16	32	RCLK Cycles	Note 3
t _{SS}	Delay from Stop to Next Start			ns	
t _{SI}	Delay from Stop to Interrupt (THRE)	8	8	RCLK Cycles	Note 3
t _{IR}	Delay from DISTR/DISTR (RD IIR) to Reset Interrupt (THRE)		250	ns	100 pF load
Modem Control					
t _{MDO}	Delay from DOSTR/DOSTR (WR MCR) to Output		200	ns	100 pF load
t _{SIM}	Delay to Set Interrupt from MODEM Input			ns	100 pF load
t _{RIM}	Delay to Reset Interrupt from DISTR/DISTR (RS MSR)		250	ns	100 pF load
Baud Generator					
N	Baud Divisor	1	2 ¹⁶ -1		
t _{BLD}	Baud Output Negative Edge Delay		125	ns	100 pF load
t _{BHD}	Baud Output Positive Edge Delay		125	ns	100 pF load
t _{LW}	Baud Output Down Time	425		ns	f _x = 2 MHz, + 2,100 pF load
t _{UW}	Baud Output Up Time	330		ns	f _x = 3 MHz, +3, 100 pF load
Receiver					
t _{SCD}	Delay from RCLK to Sample Time		2	μs	
t _{SINT}	Delay from Stop to Set Interrupt	1	1	RCLK Cycles	Note 3
t _{RINT}	Delay from DISTR/DISTR (RD RBR/RDLSR) to Reset Interrupt		1	μs	100 pF load

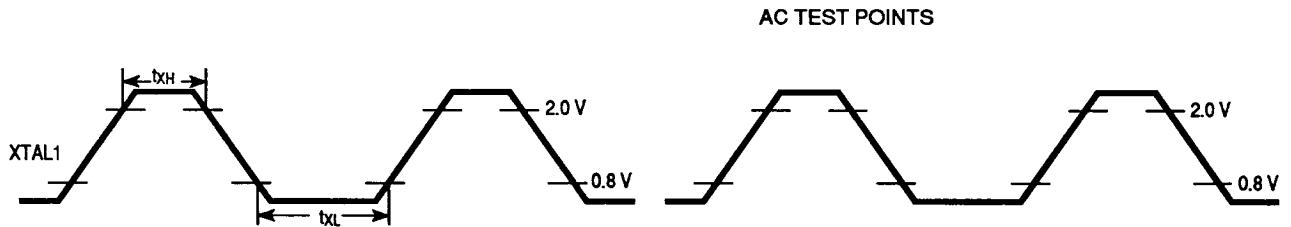
Notes:

1. Does not apply to XTAL2.
2. Applicable only when ADS is tied LOW.
3. $\text{RCLK} = t_{XH}$ and t_{XL} .
4. Charge and discharge time is determined by VOL, VOH and the external loading.
5. All timings are referenced to valid 0 and valid 1 (see AC TEST POINTS).



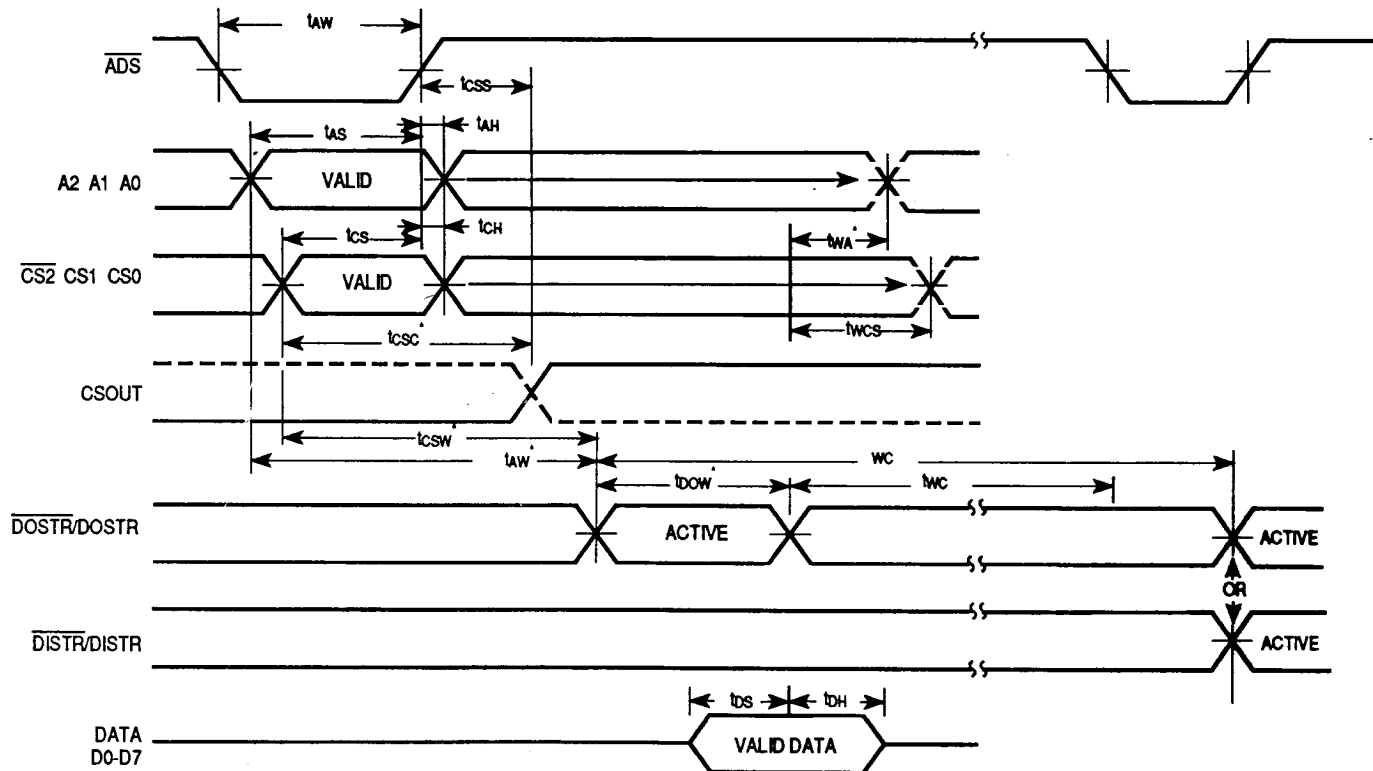
AC TESTING INPUT/OUTPUT WAVE FORM

EXTERNAL CLOCK INPUT (3.1 MHz MAXIMUM)



TIMING DIAGRAM

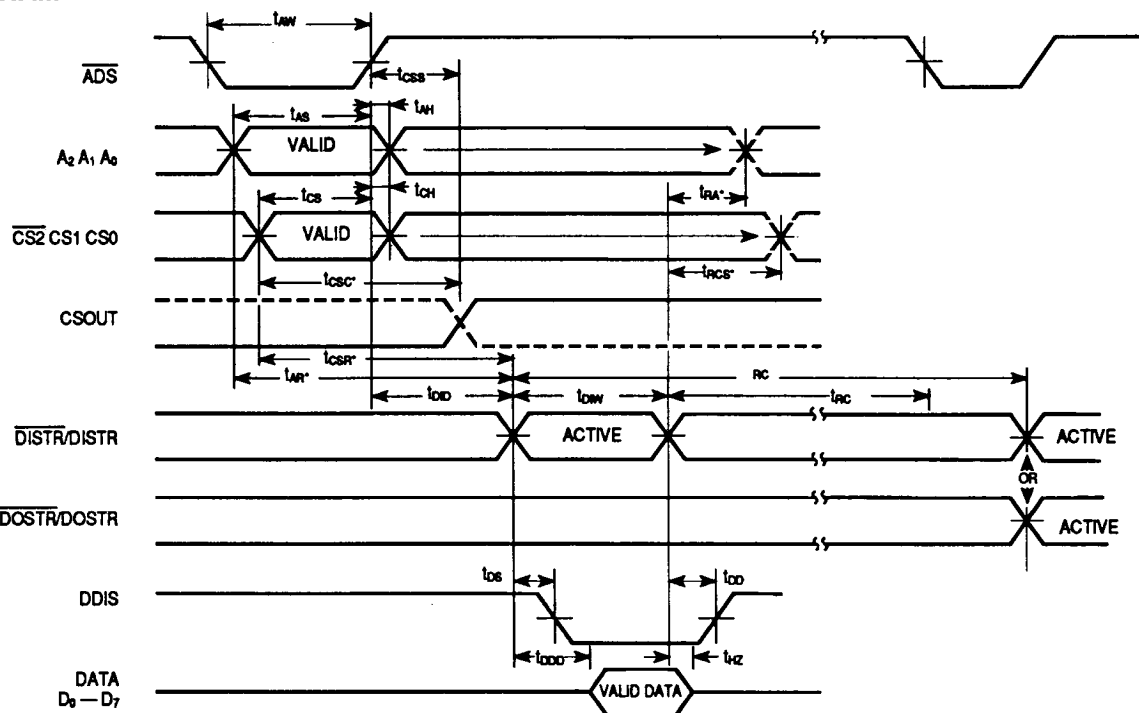
WRITE CYCLE



* Applicable only when $\overline{\text{ADS}}$ is tied low.

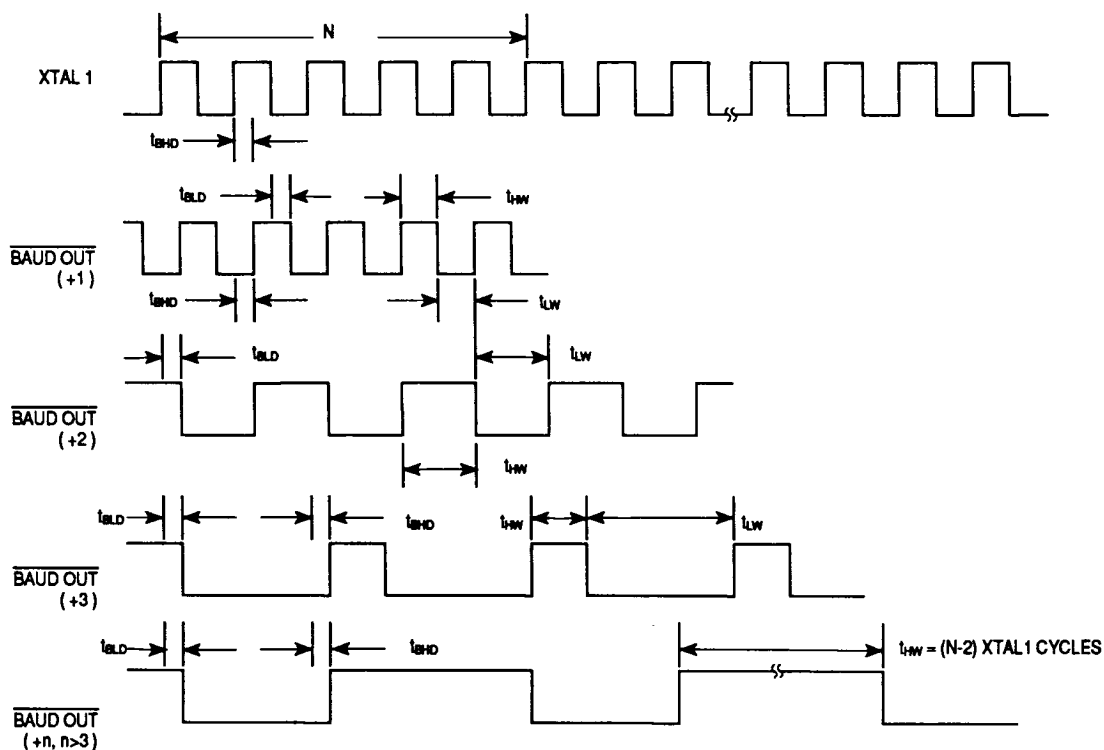


TIMING DIAGRAM READ CYCLE



* Applicable only when $\overline{ADS}$ is tied low.

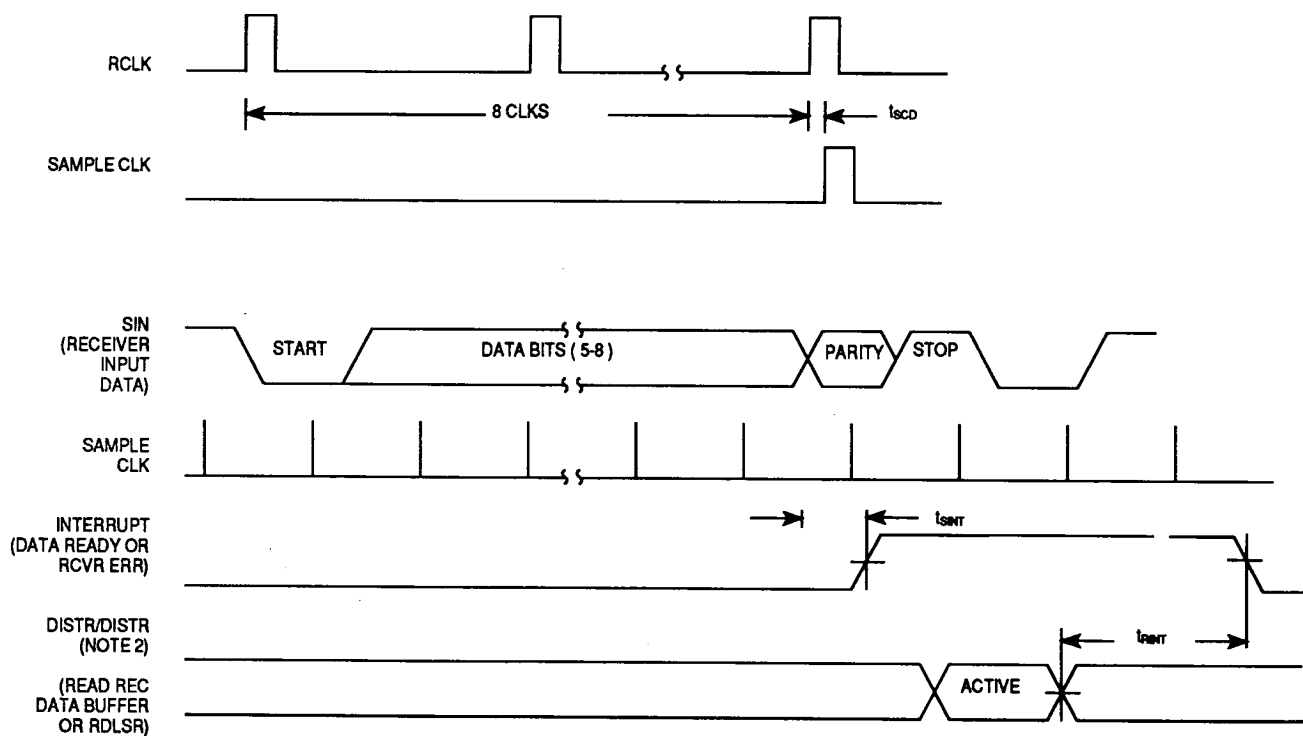
TIMING DIAGRAM BAUDOUT





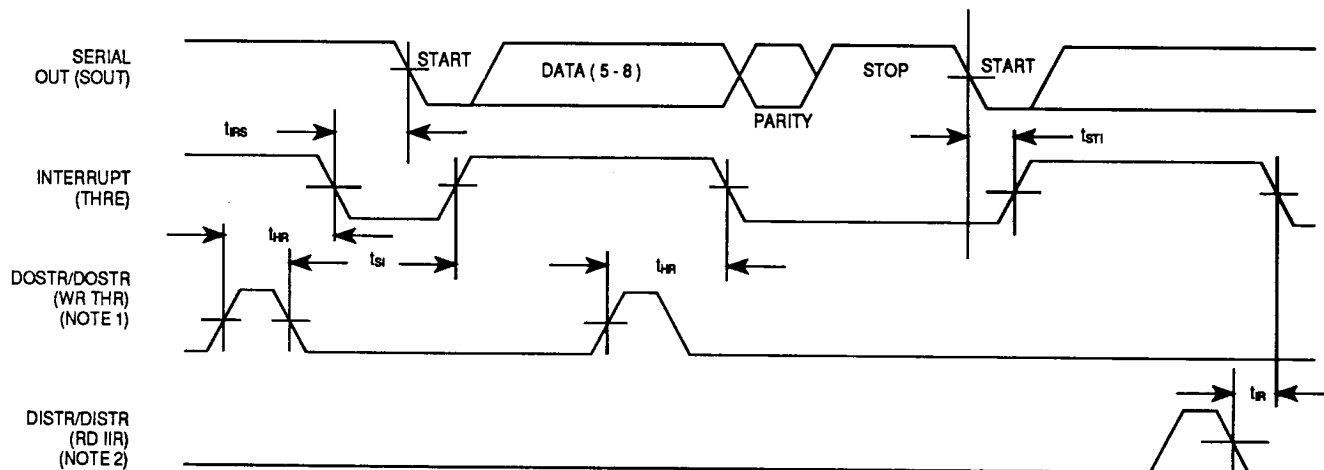
TIMING DIAGRAM

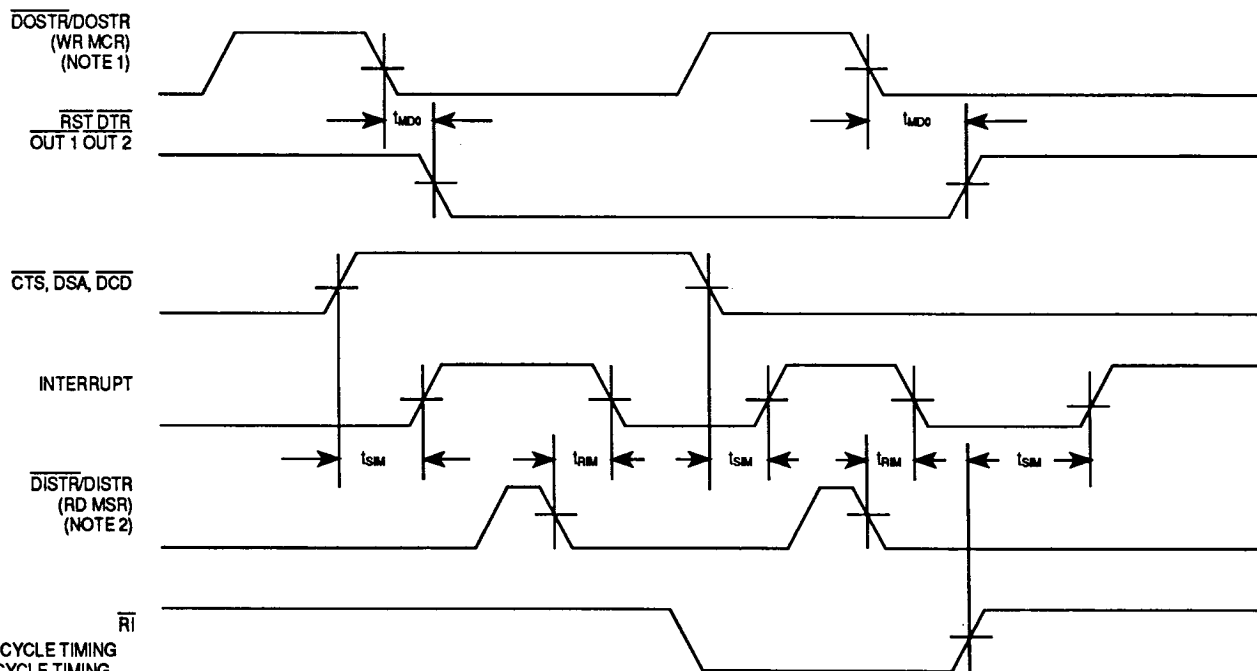
RECEIVER



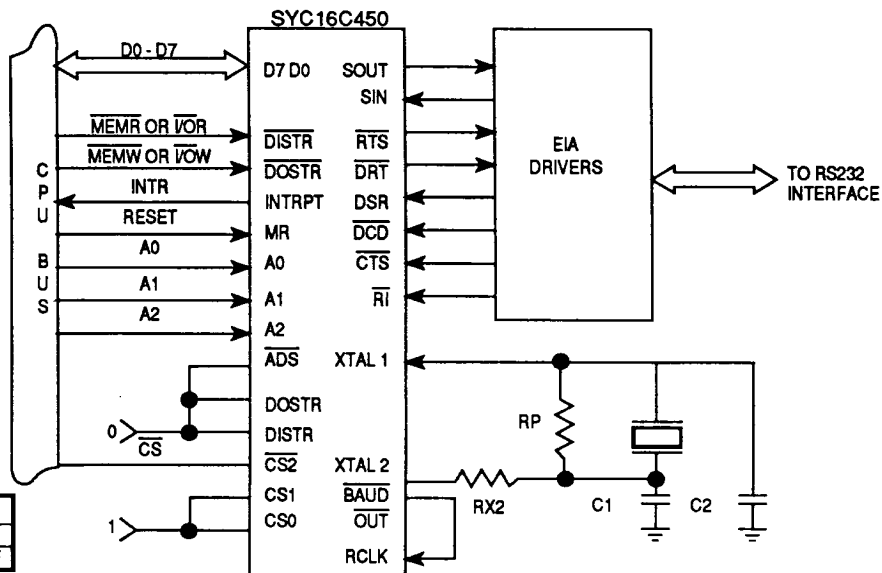
TIMING DIAGRAM

TRANSMITTER



TIMING DIAGRAM
MODEM CONTROLS

NOTES:
1. SEE WRITE CYCLE TIMING
2. SEE READ CYCLE TIMING

BASIC CONFIGURATION
SYC16C450

TYPICAL COMPONENT VALUES

Crystal	RP	RX2	C1	C2
3.072 MHz	1 M Ω	1.5 Ω	10-30 pF	40-90 pF

ORDER INFORMATION

Part Number	Maximum External Clock Frequency	Package
SYC16C450	3.1 MHz	Plastic DIP
SYC16C450-QC	3.1 MHz	Plastic Leaded Chip Carrier (PLCC)



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